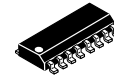


# CMOS MSI

## Quad R–S Latches

### MC14043B, MC14044B



SOIC–16  
D SUFFIX  
CASE 751B

The MC14043B and MC14044B quad R–S latches are constructed with MOS P–Channel and N–Channel enhancement mode devices in a single monolithic structure. Each latch has an independent Q output and set and reset inputs. The Q outputs are gated through three–state buffers having a common enable input. The outputs are enabled with a logical “1” or high on the enable input; a logical “0” or low disconnects the latch from the Q outputs, resulting in an open circuit at the Q outputs.

#### Features

- Double Diode Input Protection
- Three–State Outputs with Common Enable
- Outputs Capable of Driving Two Low–power TTL Loads or One Low–Power Schottky TTL Load Over the Rated Temperature Range
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable
- These Devices are Pb–Free and are RoHS Compliant

#### MAXIMUM RATINGS (Voltages Referenced to V<sub>SS</sub>)

Symbol	Parameter	Value	Unit
V <sub>DD</sub>	DC Supply Voltage Range	–0.5 to +18.0	V
V <sub>in</sub> , V <sub>out</sub>	Input or Output Voltage Range (DC or Transient)	–0.5 to V <sub>DD</sub> + 0.5	V
I <sub>in</sub> , I <sub>out</sub>	Input or Output Current (DC or Transient) per Pin	±10	mA
P <sub>D</sub>	Power Dissipation, per Package (Note 1)	500	mW
T <sub>A</sub>	Ambient Temperature Range	–55 to +125	°C
T <sub>stg</sub>	Storage Temperature Range	–65 to +150	°C
T <sub>L</sub>	Lead Temperature (8–Second Soldering)	260	°C

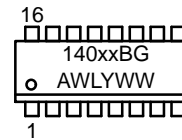
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Temperature Derating: “D/DW” Packages: –7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V<sub>in</sub> and V<sub>out</sub> should be constrained to the range V<sub>SS</sub> ≤ (V<sub>in</sub> or V<sub>out</sub>) ≤ V<sub>DD</sub>.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V<sub>SS</sub> or V<sub>DD</sub>). Unused outputs must be left open.

#### MARKING DIAGRAM



- xx = Specific Device Code
- A = Assembly Location
- WL, L = Wafer Lot
- YY, Y = Year
- WW, W = Work Week
- G = Pb–Free Indicator

#### ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

# MC14043B, MC14044B

## PIN ASSIGNMENT



NC = NO CONNECTION

Figure 1.

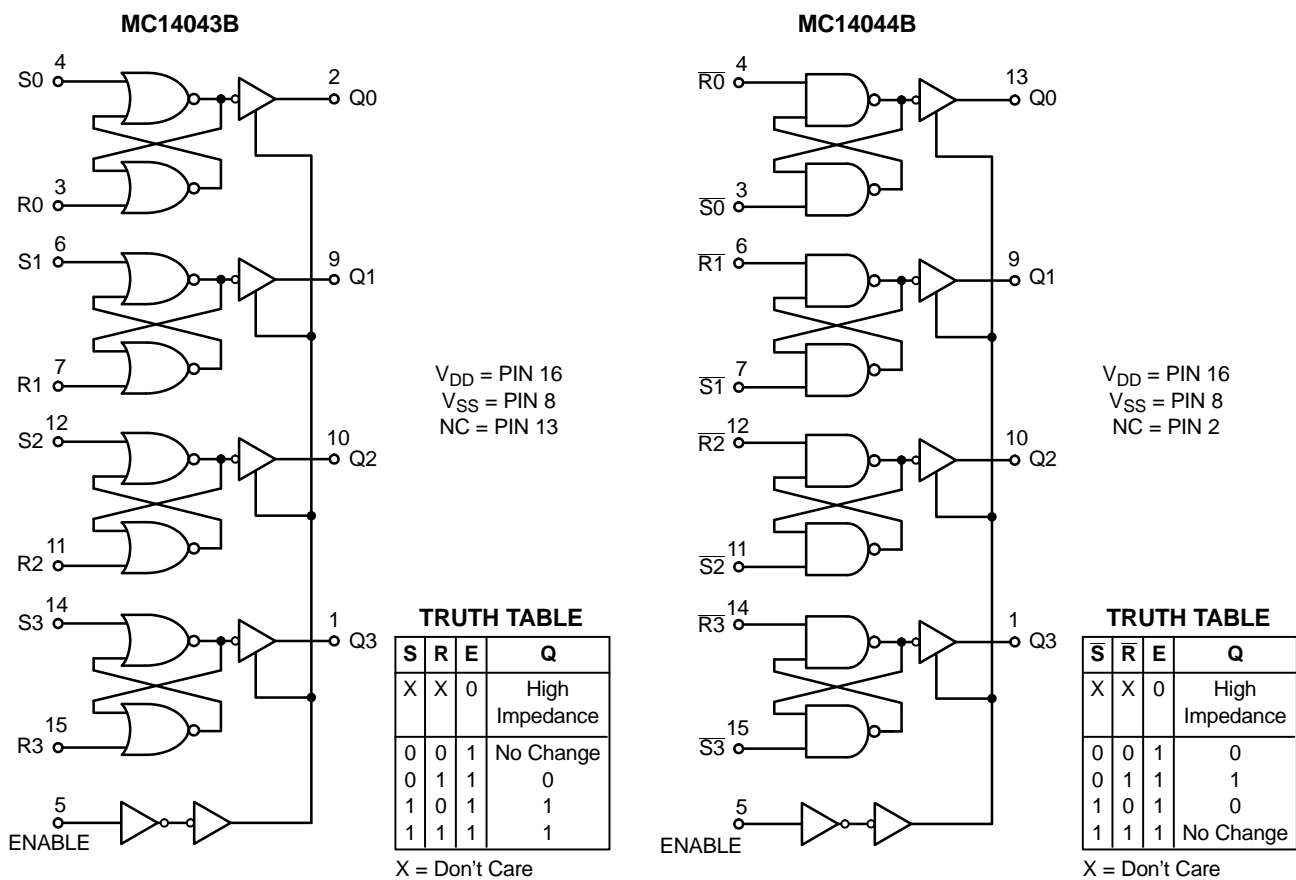


Figure 2.

# MC14043B, MC14044B

## ELECTRICAL CHARACTERISTICS (Voltages Referenced to $V_{SS}$ )

Characteristic	Symbol	$V_{DD}$ Vdc	- 55°C		25°C			125°C		Unit	
			Min	Max	Min	Typ (Note 2)	Max	Min	Max		
Output Voltage $V_{in} = V_{DD}$ or 0	"0" Level $V_{OL}$	5.0	–	0.05	–	0	0.05	–	0.05	Vdc	
		10	–	0.05	–	0	0.05	–	0.05		
		15	–	0.05	–	0	0.05	–	0.05		
	"1" Level $V_{in} = 0$ or $V_{DD}$	$V_{OH}$	5.0	4.95	–	4.95	5.0	–	4.95	–	Vdc
			10	9.95	–	9.95	10	–	9.95	–	
			15	14.95	–	14.95	15	–	14.95	–	
Input Voltage ( $V_O = 4.5$ or $0.5$ Vdc) ( $V_O = 9.0$ or $1.0$ Vdc) ( $V_O = 13.5$ or $1.5$ Vdc)	"0" Level $V_{IL}$	5.0	–	1.5	–	2.25	1.5	–	1.5	Vdc	
		10	–	3.0	–	4.50	3.0	–	3.0		
		15	–	4.0	–	6.75	4.0	–	4.0		
	"1" Level ( $V_O = 0.5$ or $4.5$ Vdc) ( $V_O = 1.0$ or $9.0$ Vdc) ( $V_O = 1.5$ or $13.5$ Vdc)	$V_{IH}$	5.0	3.5	–	3.5	2.75	–	3.5	–	Vdc
			10	7.0	–	7.0	5.50	–	7.0	–	
			15	11	–	11	8.25	–	11	–	
Output Drive Current ( $V_{OH} = 2.5$ Vdc) ( $V_{OH} = 4.6$ Vdc) ( $V_{OH} = 9.5$ Vdc) ( $V_{OH} = 13.5$ Vdc)	Source $I_{OH}$	5.0	–3.0	–	–2.4	–4.2	–	–1.7	–	mA <sub>dc</sub>	
		5.0	–0.64	–	–0.51	–0.88	–	–0.36	–		
		10	–1.6	–	–1.3	–2.25	–	–0.9	–		
		15	–4.2	–	–3.4	–8.8	–	–2.4	–		
	Sink $I_{OL}$	5.0	0.64	–	0.51	0.88	–	0.36	–	mA <sub>dc</sub>	
		10	1.6	–	1.3	2.25	–	0.9	–		
15		4.2	–	3.4	8.8	–	2.4	–			
Input Current	$I_{in}$	15	–	±0.1	–	±0.00001	±0.1	–	±1.0	μA <sub>dc</sub>	
Input Capacitance ( $V_{in} = 0$ )	$C_{in}$	–	–	–	–	5.0	7.5	–	–	pF	
Quiescent Current (Per Package)	$I_{DD}$	5.0	–	1.0	–	0.002	1.0	–	30	μA <sub>dc</sub>	
		10	–	2.0	–	0.004	2.0	–	60		
		15	–	4.0	–	0.006	4.0	–	120		
Total Supply Current (Notes 3 & 4) (Dynamic plus Quiescent, Per Package) ( $C_L = 50$ pF on all outputs all buffers switching)	$I_T$	5.0	$I_T = (0.58 \mu A/kHz) f + I_{DD}$							μA <sub>dc</sub>	
		10	$I_T = (1.15 \mu A/kHz) f + I_{DD}$								
		15	$I_T = (1.73 \mu A/kHz) f + I_{DD}$								
Three-State Output Leakage Current	$I_{TL}$	15	–	±0.1	–	±0.0001	±0.1	–	±3.0	μA <sub>dc</sub>	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

3. The formulas given are for the typical characteristics only at 25°C.

4. To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where:  $I_T$  is in μA (per package),  $C_L$  in pF,  $V = (V_{DD} - V_{SS})$  in volts,  $f$  in kHz is input frequency, and  $k = 0.004$ .

# MC14043B, MC14044B

## SWITCHING CHARACTERISTICS (Note 5) ( $C_L = 50$ pF, $T_A = 25^\circ\text{C}$ )

Characteristic	Symbol	$V_{DD}$ Vdc	Min	Typ (Note 6)	Max	Unit
Output Rise Time $t_{TLH} = (1.35 \text{ ns/pF}) C_L + 32.5 \text{ ns}$ $t_{TLH} = (0.60 \text{ ns/pF}) C_L + 20 \text{ ns}$ $t_{TLH} = (0.40 \text{ ns/pF}) C_L + 20 \text{ ns}$	$t_{TLH}$	5.0 10 15	– – –	100 50 40	200 100 80	ns
Output Fall Time $t_{THL} = (1.35 \text{ ns/pF}) C_L + 32.5 \text{ ns}$ $t_{THL} = (0.60 \text{ ns/pF}) C_L + 20 \text{ ns}$ $t_{THL} = (0.40 \text{ ns/pF}) C_L + 20 \text{ ns}$	$t_{THL}$	5.0 10 15	– – –	100 50 40	200 100 80	ns
Propagation Delay Time $t_{PLH} = (0.90 \text{ ns/pF}) C_L + 130 \text{ ns}$ $t_{PLH} = (0.36 \text{ ns/pF}) C_L + 57 \text{ ns}$ $t_{PLH} = (0.26 \text{ ns/pF}) C_L + 47 \text{ ns}$ $t_{PHL} = (0.90 \text{ ns/pF}) C_L + 130 \text{ ns}$ $t_{PHL} = (0.90 \text{ ns/pF}) C_L + 57 \text{ ns}$ $t_{PHL} = (0.26 \text{ ns/pF}) C_L + 47 \text{ ns}$	$t_{PLH}$    $t_{PHL}$	5.0 10 15  5.0 10 15	– – –  – – –	175 75 60  175 75 60	350 175 120  350 175 120	ns    ns
Set, $\overline{\text{Set}}$ Pulse Width	$t_W$	5.0 10 15	200 100 70	80 40 30	– – –	ns
Reset, $\overline{\text{Reset}}$ Pulse Width	$t_W$	5.0 10 15	200 100 70	80 40 30	– – –	ns
Three-State Enable/Disable Delay	$t_{PLZ}$ , $t_{PHZ}$ , $t_{PZL}$ , $t_{PZH}$	5.0 10 15	– – –	150 80 55	300 160 110	ns

5. The formulas given are for the typical characteristics only at  $25^\circ\text{C}$ .

6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

## AC WAVEFORMS

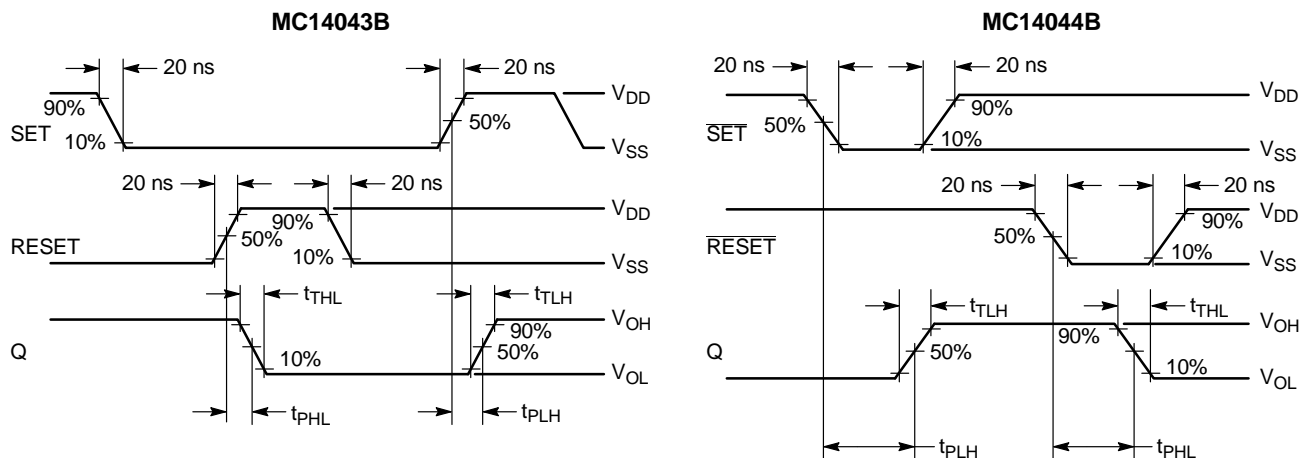


Figure 3.

# MC14043B, MC14044B

## THREE-STATE ENABLE/DISABLE DELAYS

### Set, Reset, Enable, and Switch Conditions for 3-State Tests

Test	Enable	S1	S2	Q	MC14043B		MC14044B	
					S	R	$\bar{S}$	R
t <sub>PZH</sub>	↗	Open	Closed	A	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>
t <sub>PZL</sub>	↘	Closed	Open	B	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DD</sub>	V <sub>SS</sub>
t <sub>PHZ</sub>	↘	Open	Closed	A	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>
t <sub>PLZ</sub>	↗	Closed	Open	B	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DD</sub>	V <sub>SS</sub>

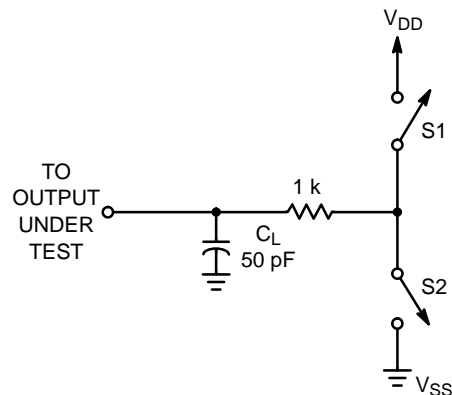


Figure 4.

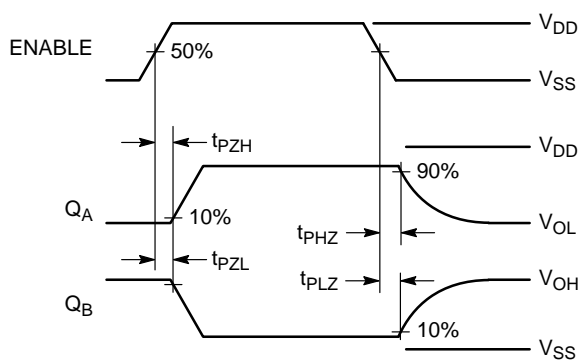


Figure 5.

### ORDERING INFORMATION

Device	Package	Shipping†
MC14043BDG	SOIC-16 (Pb-Free)	48 Units / Rail
NLV14043BDG*	SOIC-16 (Pb-Free)	48 Units / Rail
MC14043BDR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
NLV14043BDR2G*	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel

MC14044BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14044BDR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
NLV14044BDR2G*	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



SCALE 1:1

## SOIC-16 CASE 751B-05 ISSUE K

DATE 29 DEC 2006



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

- |  |  |  |  |
|--|--|--|--|
| <p><b>STYLE 1:</b></p> <p>PIN 1. COLLECTOR<br/>2. BASE<br/>3. EMITTER<br/>4. NO CONNECTION<br/>5. EMITTER<br/>6. BASE<br/>7. COLLECTOR<br/>8. COLLECTOR<br/>9. BASE<br/>10. EMITTER<br/>11. NO CONNECTION<br/>12. EMITTER<br/>13. BASE<br/>14. COLLECTOR<br/>15. EMITTER<br/>16. COLLECTOR</p>                           | <p><b>STYLE 2:</b></p> <p>PIN 1. CATHODE<br/>2. ANODE<br/>3. NO CONNECTION<br/>4. CATHODE<br/>5. CATHODE<br/>6. NO CONNECTION<br/>7. ANODE<br/>8. CATHODE<br/>9. CATHODE<br/>10. ANODE<br/>11. NO CONNECTION<br/>12. CATHODE<br/>13. CATHODE<br/>14. NO CONNECTION<br/>15. ANODE<br/>16. CATHODE</p> | <p><b>STYLE 3:</b></p> <p>PIN 1. COLLECTOR, DYE #1<br/>2. BASE, #1<br/>3. EMITTER, #1<br/>4. COLLECTOR, #1<br/>5. COLLECTOR, #2<br/>6. BASE, #2<br/>7. EMITTER, #2<br/>8. COLLECTOR, #2<br/>9. COLLECTOR, #3<br/>10. BASE, #3<br/>11. EMITTER, #3<br/>12. COLLECTOR, #3<br/>13. COLLECTOR, #4<br/>14. BASE, #4<br/>15. EMITTER, #4<br/>16. COLLECTOR, #4</p>   | <p><b>STYLE 4:</b></p> <p>PIN 1. COLLECTOR, DYE #1<br/>2. COLLECTOR, #1<br/>3. COLLECTOR, #2<br/>4. COLLECTOR, #2<br/>5. COLLECTOR, #3<br/>6. COLLECTOR, #3<br/>7. COLLECTOR, #4<br/>8. COLLECTOR, #4<br/>9. BASE, #4<br/>10. EMITTER, #4<br/>11. BASE, #3<br/>12. EMITTER, #3<br/>13. BASE, #2<br/>14. EMITTER, #2<br/>15. BASE, #1<br/>16. EMITTER, #1</p> |
| <p><b>STYLE 5:</b></p> <p>PIN 1. DRAIN, DYE #1<br/>2. DRAIN, #1<br/>3. DRAIN, #2<br/>4. DRAIN, #2<br/>5. DRAIN, #3<br/>6. DRAIN, #3<br/>7. DRAIN, #4<br/>8. DRAIN, #4<br/>9. GATE, #4<br/>10. SOURCE, #4<br/>11. GATE, #3<br/>12. SOURCE, #3<br/>13. GATE, #2<br/>14. SOURCE, #2<br/>15. GATE, #1<br/>16. SOURCE, #1</p> | <p><b>STYLE 6:</b></p> <p>PIN 1. CATHODE<br/>2. CATHODE<br/>3. CATHODE<br/>4. CATHODE<br/>5. CATHODE<br/>6. CATHODE<br/>7. CATHODE<br/>8. CATHODE<br/>9. ANODE<br/>10. ANODE<br/>11. ANODE<br/>12. ANODE<br/>13. ANODE<br/>14. ANODE<br/>15. ANODE<br/>16. ANODE</p>                                 | <p><b>STYLE 7:</b></p> <p>PIN 1. SOURCE N-CH<br/>2. COMMON DRAIN (OUTPUT)<br/>3. COMMON DRAIN (OUTPUT)<br/>4. GATE P-CH<br/>5. COMMON DRAIN (OUTPUT)<br/>6. COMMON DRAIN (OUTPUT)<br/>7. COMMON DRAIN (OUTPUT)<br/>8. SOURCE P-CH<br/>9. SOURCE P-CH<br/>10. COMMON DRAIN (OUTPUT)<br/>11. COMMON DRAIN (OUTPUT)<br/>12. COMMON DRAIN (OUTPUT)<br/>13. GATE N-CH<br/>14. COMMON DRAIN (OUTPUT)<br/>15. COMMON DRAIN (OUTPUT)<br/>16. SOURCE N-CH</p> |  |

### SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

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